Lattice Semiconductor Corporation - LFSCM3GA115EP1-5FC1704I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	28750
Number of Logic Elements/Cells	115000
Total RAM Bits	7987200
Number of I/O	942
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	1704-BCBGA, FCBGA
Supplier Device Package	1704-CFCBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga115ep1-5fc1704i

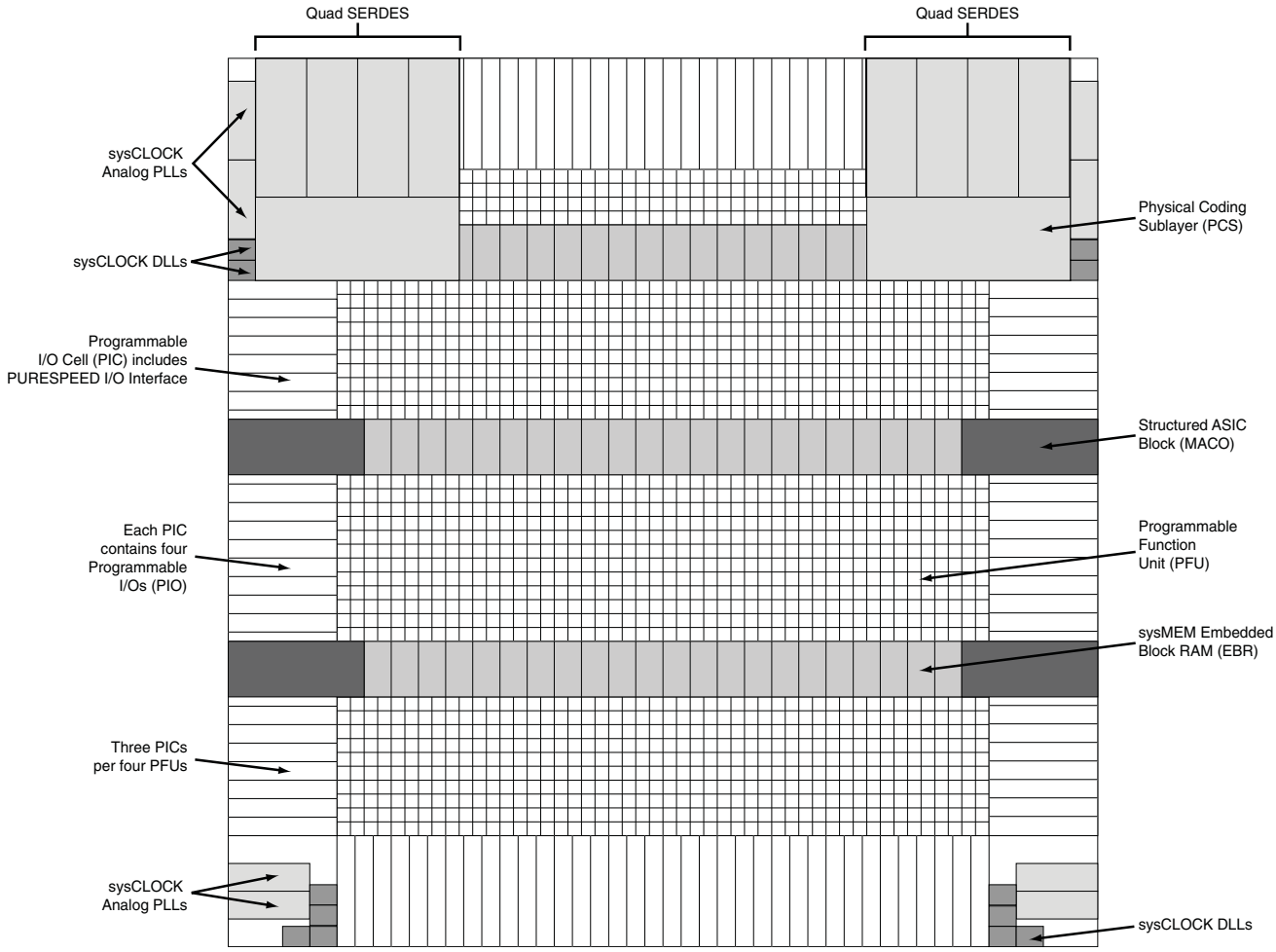
LatticeSC/M Family Data Sheet Introduction

January 2010 Data Sheet DS1004

Features

- **High Performance FPGA Fabric**
  - 15K to 115K four input Look-up Tables (LUT4s)
  - 139 to 942 I/Os
  - 700MHz global clock; 1GHz edge clocks
- **4 to 32 High Speed SERDES and flexiPCS™ (per Device)**
  - Performance ranging from 600Mbps to 3.8Gbps
  - Excellent Rx jitter tolerance (0.8UI at 3.125Gbps)
  - Low Tx jitter (0.25UI typical at 3.125Gbps)
  - Built-in Pre-emphasis and equalization
  - Low power (typically 105mW per channel)
  - Embedded Physical Coding Sublayer (PCS) provides pre-engineered implementation for the following standards:
    - GbE, XAUI, PCI Express, SONET, Serial RapidIO, 1G Fibre Channel, 2G Fibre Channel
- **2Gbps High Performance PURESPEED™ I/O**
  - Supports the following performance bandwidths
    - Differential I/O up to 2Gbps DDR (1GHz Clock)
    - Single-ended memory interfaces up to 800Mbps
  - 144 Tap programmable Input Delay (INDEL) block on every I/O dynamically aligns data to clock for robust performance
    - Dynamic bit Adaptive Input Logic (AIL) monitoring and control circuitry per pin that automatically ensures proper set-up and hold
    - Dynamic bus: uses control bus from DLL
    - Static per bit
  - Electrical standards supported:
    - LVCMOS 3.3/2.5/1.8/1.5/1.2, LVTTL
    - SSTL 3/2/18 I, II; HSTL 18/15 I, II
    - PCI, PCI-X
    - LVDS, Mini-LVDS, Bus-LVDS, MLVDS, LVPECL, RSDS
  - Programmable On Die Termination (ODT)
    - Includes Thevenin Equivalent and low power V_{TT} termination options
- **Memory Intensive FPGA**
  - sysMEM™ embedded Block RAM
    - 1 to 7.8 Mbits memory
    - True Dual Port/Pseudo Dual Port/Single Port
    - Dedicated FIFO logic for all block RAM
    - 500MHz performance
  - Additional 240K to 1.8Mbits distributed RAM
- **sysCLOCK™ Network**
  - Eight analog PLLs per device
    - Frequency range from 15MHz to 1GHz
    - Spread spectrum support
  - 12 DLLs per device with direct control of I/O delay
    - Frequency range from 100MHz to 700MHz
  - Extensive clocking network
    - 700MHz primary and 325 MHz secondary clocks
    - 1GHz I/O-connected edge clocks
  - Precision Clock Divider
    - Phase matched x2 and x4 division of incoming clocks
  - Dynamic Clock Select (DCS)
    - Glitch free clock MUX
- **Masked Array for Cost Optimization (MACO™) Blocks**
  - On-chip structured ASIC Blocks provide pre-engineered IP for low power, low cost system level integration
- **High Performance System Bus**
  - Ties FPGA elements together with a standard bus framework
    - Connects to peripheral user interfaces for run-time dynamic configuration
- **System Level Support**
  - IEEE standard 1149.1 Boundary Scan, plus ispTRACY™ internal logic analyzer
  - IEEE Standard 1532 in-system configuration
  - 1.2V and 1.0V operation
  - Onboard oscillator for initialization and general use
  - Embedded PowerPC microprocessor interface
  - Low cost wire-bond and high pin count flip-chip packaging
  - Low cost SPI Flash RAM configuration

Figure 2-1. Simplified Block Diagram (Top Level)



Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM and ROM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SPR 16x2 DPR 16x2	ROM 16x2

Logic Mode

In this mode, the LUTs in each Slice are configured as combinatorial lookup tables. A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7 and LUT8 can be constructed by concatenating other Slices in the PFU.

Ripple Mode

Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Up counter 2-bit
- Down counter 2-bit
- Comparator functions of A and B inputs
  - A greater-than-or-equal-to B
  - A not-equal-to B
  - A less-than-or-equal-to B

Ripple Mode includes an optional configuration that performs arithmetic using fast carry chain methods. In this configuration (also referred to as CCU2 mode) two additional signals, Carry Generate and Carry Propagate, are generated on a per slice basis to allow fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode

In this mode, distributed RAM can be constructed using each LUT block as a 16x1-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

The Lattice design tools support the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the Slice. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Dual port memories involve the pairing of two Slices, one Slice functions as the read-write port. The other companion Slice supports the read-only port. For more information on RAM mode, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required For Implementing Distributed RAM

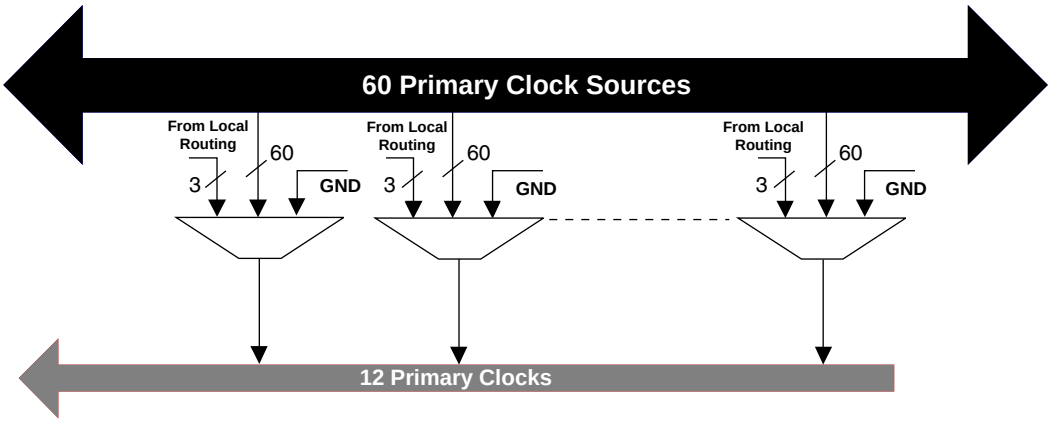
	SPR16x2	DPR16x2
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

ROM Mode

The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

Figure 2-6. Per Quadrant Clock Selection



Note: GND is available to switch off the network.

Secondary Clocks

In addition to the primary clock network and edge clocks the LatticeSC devices also contain a secondary clock network. Built of X6 style routing elements this secondary clock network is ideal for routing slower speed clock and control signals throughout the device preserving high-speed clock networks for the most timing critical signals.

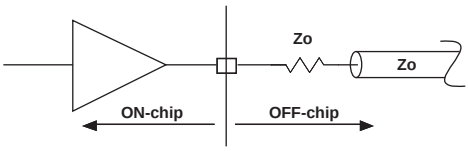
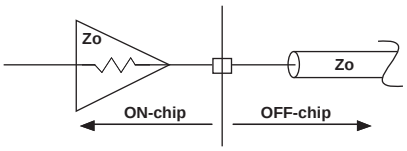
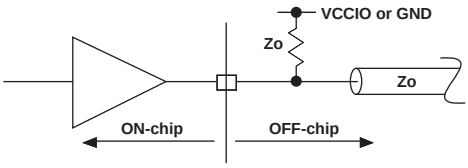
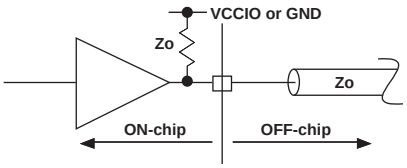
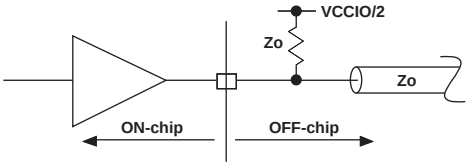
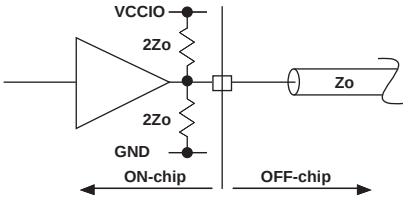
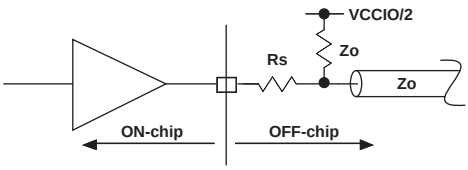
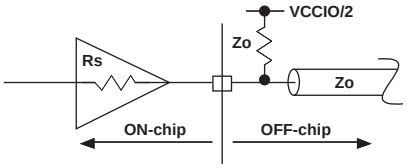
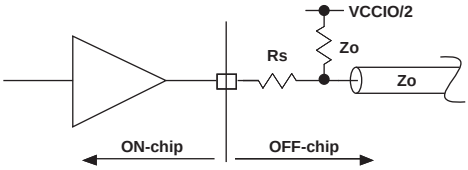
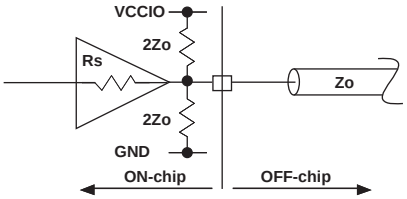
Edge Clocks

LatticeSC devices have a number of high-speed edge clocks that are intended for use with the PIOs in the implementation of high-speed interfaces. There are eight edge clocks per bank for the top and bottom of the device. The left and right sides have eight edge clocks per side for both banks located on that side. Figure 2-7 shows the arrangement of edge clocks.

Edge clock resources can be driven from a variety of sources. Edge clock resources can be driven from:

- Edge clock PIOs in the same bank
- Primary clock PIOs in the same bank
- Routing
- Adjacent PLLs and DLLs
- ELSR output from the clock divider

Figure 2-27. Output Termination Schemes

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Series termination (controlled output impedance)		
Parallel termination to V_{CCIO}, or parallel driving end		
Parallel termination to $V_{CCIO}/2$ driving end		
Combined series + parallel termination to $V_{CCIO}/2$ at driving end (only series termination moved on-chip)		
Combined series + parallel to $V_{CCIO}/2$ driving end		

RSDS

Over Recommended Operating Conditions

Parameter Symbol	Description	Min.	Typ.	Max.	Units
V_{OD}	Output voltage, differential, R_T = 100 ohms	100	200	600	mV
V_{OS}	Output voltage, common mode	0.5	1.2	1.5	V
I_{RSDS}	Differential driver output current	1	2	6	mA
V_{THD}	Input voltage differential	100	—	—	mV
V_{CM}	Input common mode voltage	0.3	—	1.5	V
T_R, T_F	Output rise and fall times, 20% to 80%	—	500	—	ps
T_{ODUTY}	Output clock duty cycle	45	50	55	%

Note: Data is for 2mA drive. Other differential driver current options are available.

LVPECL

The LatticeSC devices support differential LVPECL standard. This standard is emulated using controlled impedance complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

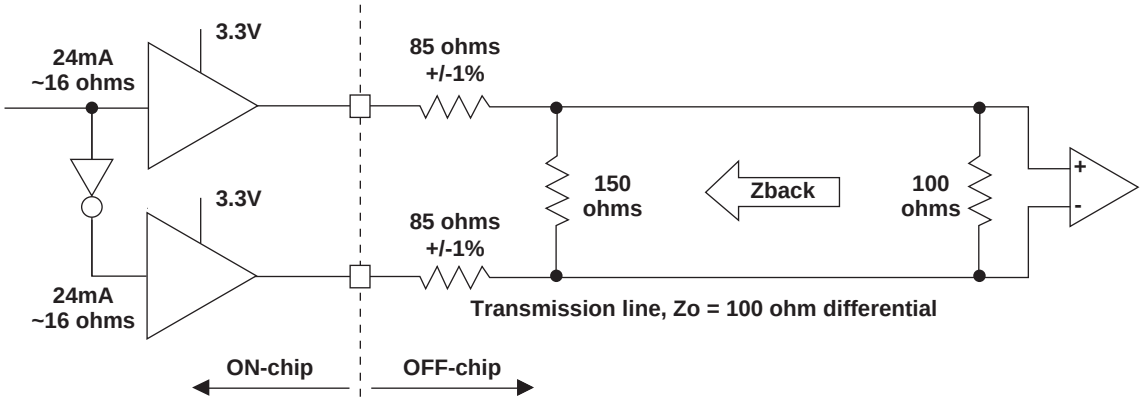


Table 3-3. LVPECL DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Nominal	Units
Z_{OUT}	Output impedance	16	ohm
R_S	Driver series resistor	85	ohm
R_P	Driver parallel resistor	150	ohm
R_T	Receiver termination	100	ohm
V_{OH}	Output high voltage	2.03	V
V_{OL}	Output low voltage	1.27	V
V_{OD}	Output differential voltage	0.76	V
V_{CM}	Output common mode voltage	1.65	V
Z_{BACK}	Back impedance	86	ohm
I_{DC}	DC output current	12.6	mA

1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS, MLVDS and other differential interfaces please see details of additional technical documentation at the end of this data sheet.

On-die Differential Common Mode Termination

Symbol	Description	Min.	Typ.	Max.	Units
C_{CMT}	Capacitance V_{CMT} to GND	—	40	—	pF

LatticeSC/M External Switching Characteristics[3]

Over Recommended Commercial Operating Conditions at VCC = 1.2V +/- 5%

Parameter	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (using Primary Clock without PLL)[2]								
t_{CO}	Global Clock Input to Output - PIO Output Register	2.83	5.74	2.83	6.11	2.83	6.49	ns
t_{SU}	Global Clock Input Setup - PIO Input Register without fixed input delay	-0.66	—	-0.66	—	-0.66	—	ns
t_{H}	Global Clock Input Hold - PIO Input Register without fixed input delay	1.73	—	1.95	—	2.16	—	ns
t_{SU_IDLY}	Global Clock Input Setup - PIO Input Register with input delay	0.86	—	1.03	—	1.20	—	ns
t_{H_IDLY}	Global Clock Input Hold - PIO Input Register with input delay	-0.17	—	-0.17	—	-0.17	—	ns
f_{MAX_PFU}	Global Clock frequency of PFU register	—	700	—	700	—	700	MHz
f_{MAX_IO}	Global Clock frequency of I/O register	—	1000	—	1000	—	1000	MHz
t_{GC_SKEW}	Global Clock skew	—	89	—	103	—	116	ps
General I/O Pin Parameters (using Primary Clock with PLL)[1, 2]								
t_{CO}	Global Clock Input to Output - PIO Output Register	2.25	4.81	2.25	5.08	2.25	5.37	ns
t_{SU}	Global Clock Input Setup - PIO Input Register without fixed input delay	-0.07	—	-0.07	—	-0.07	—	ns
t_{H}	Global Clock Input Hold - PIO Input Register without fixed input delay	0.80	—	0.93	—	1.04	—	ns
General I/O Pin Parameters (using Edge Clock without PLL)[2]								
t_{CO}	Edge Clock Input to Output - PIO Output Register	2.38	4.77	2.38	5.04	2.38	5.33	ns
t_{SU}	Edge Clock Input Setup - PIO Input Register without fixed input delay	-0.08	—	-0.08	—	-0.08	—	ns
t_{H}	Edge Clock Input Hold - PIO Input Register	0.49	—	0.58	—	0.66	—	ns
t_{SU_IDLY}	Edge Clock Input Setup - PIO Input Register with input delay	0.81	—	0.97	—	1.12	—	ns
t_{H_IDLY}	Edge Clock Input Hold - PIO Input Register with input delay	-0.34	—	-0.34	—	-0.34	—	ns
t_{EC_SKEW}	Edge Clock skew	—	28	—	32	—	36	ps
General I/O Pin Parameters (using Latch FF without PLL)[2]								
t_{SU}	Latch FF, Input Setup - PIO Input Register without fixed input delay	-0.14	—	-0.14	—	-0.14	—	ns
t_{H}	Latch FF, Input Hold - PIO Input Register without fixed input delay	0.58	—	0.68	—	0.77	—	ns
t_{SU_IDLY}	Latch FF, Input Setup - PIO Input Register with input delay	0.70	—	0.68	—	0.77	—	ns
t_{H_IDLY}	Latch FF, Input Hold - PIO Input Register with input delay	-0.30	—	-0.30	—	-0.30	—	ns

1. No PLL delay tuning (clock injection removal mode, system clock feedback).
2. Using LVCMOS25 12mA I/O. Timing adders for other supported I/O technologies are specified in the LatticeSC Family Timing Adders table.
3. Complete Timing Parameters for a user design are incorporated when running ispLEVER. This is a sampling of the key timing parameters. Timing specs are for non-AIL applications.

LatticeSC/M Internal Timing Parameters[1]

Over Recommended Commercial Operating Conditions at VCC = 1.2V +/- 5%

Parameter	Symbol	Description	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
PFU Logic Mode Timing									
t_{LUT4_PFU}	CTOF_DEL	LUT4 delay (A to D inputs to F output)	—	0.045	—	0.050	—	0.054	ns
t_{LUT5_PFU}	MTOOFX_DEL	LUT5 delay (inputs to output)	—	0.152	—	0.172	—	0.192	ns
t_{LSR_PFU}	LSR_DEL	Set/Reset to output (asynchronous)	—	0.378	—	0.426	—	0.474	ns
t_{SUM_PFU}	M_SET	Clock to Mux (M0,M1) input setup time	0.113	—	0.131	—	0.148	—	ns
t_{HM_PFU}	M_HLD	Clock to Mux (M0,M1) input hold time	-0.041	—	-0.046	—	-0.052	—	ns
t_{SUD_PFU}	DIN_SET	Clock to D input setup time	0.072	—	0.083	—	0.094	—	ns
t_{HD_PFU}	DIN_HLD	Clock to D input hold time	-0.028	—	-0.032	—	-0.035	—	ns
t_{CK2Q_PFU}	REG_DEL	Clock to Q delay, D-type register configuration	—	0.224	—	0.252	—	0.279	ns
t_{LE2Q_PFU}	LTCH_DEL	Clock to Q delay latch configuration	—	0.294	—	0.331	—	0.367	ns
t_{LD2Q_PFU}	TLTCH_DEL	D to Q throughput delay when latch is enabled	—	0.300	—	0.338	—	0.376	ns
PFU Memory Mode Timing									
t_{CORAM_PFU}	CLKTOF_DEL	Clock to Output	—	0.575	—	0.649	—	0.724	ns
t_{SUDATA_PFU}	DIN_SET	Data Setup Time	-0.024	—	-0.026	—	-0.027	—	ns
t_{HDATA_PFU}	DIN_HLD	Data Hold Time	0.075	—	0.084	—	0.094	—	ns
t_{SUADDR_PFU}	WAD_SET	Address Setup Time	-0.176	—	-0.196	—	-0.215	—	ns
t_{HADDR_PFU}	WAD_HLD	Address Hold Time	0.110	—	0.124	—	0.138	—	ns
t_{SUWREN_PFU}	WE_SET	Write/Read Enable Setup Time	0.014	—	0.019	—	0.024	—	ns
t_{HWREN_PFU}	WE_HLD	Write/Read Enable Hold Time	0.078	—	0.086	—	0.094	—	ns
PIC Timing									
PIO Input/Output Buffer Timing									
t_{IN_PIO}	IN_DEL	Input Buffer Delay(LVCMOS25)	—	0.578	—	0.661	—	0.744	ns
t_{OUT_PIO}	DOPADI_DEL	Output Buffer Delay(LVCMOS25)	—	2.712	—	3.027	—	3.395	ns
t_{SUI_PIO}	DIN_SET	Input Register Setup Time (Data Before Clock)	0.277	—	0.312	—	0.348	—	ns
t_{HI_PIO}	DIN_HLD	Input Register Hold Time (Data after Clock)	-0.267	—	-0.306	—	-0.345	—	ns
t_{COO_PIO}	CK_DEL	Output Register Clock to Output Delay	—	0.513	—	0.571	—	0.639	ns
t_{SUCE_PIO}	CE_SET	Input Register Clock Enable Setup Time	—	0.000	—	0.000	—	0.000	ns
t_{HCE_PIO}	CE_HLD	Input Register Clock Enable Hold Time	—	0.129	—	0.145	—	0.161	ns
t_{SULSR_PIO}	LSR_SET	Set/Reset Setup Time	0.057	—	0.060	—	0.063	—	ns
t_{HLSR_PIO}	LSR_HLD	Set/Reset Hold Time	-0.151	—	-0.159	—	-0.169	—	ns
t_{LE2Q_PIO}	CK_DEL	Input Register Clock to Q delay latch configuration	—	0.335	—	0.372	—	0.410	ns
t_{LD2Q_PIO}	DIN_DEL	Input Register D to Q throughput delay when latch is enabled	—	0.578	—	0.647	—	0.717	ns

Input Delay Block/AIL Timing

Parameter	Description	Min.	Typ.	Max.	Units
t_{FDEL}	Fine delay time	35	45	80	ps
t_{CDEL}	Coarse delay time	1120	1440	2560	ps
jt_{AIL}	AIL jitter tolerance	1- ((N^1 * t_{FDEL}) / (Clock Period))			UI

1. N = number of fine delays used in a particular AIL setting

GSR Timing

Parameter	Description	VCC	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
$t_{SYNC\_GSR\_MAX}$	Maximum operating frequency for synchronous GSR	1.14V	—	438	—	417	—	398	MHz
		0.95V	—	378	—	355	—	337	MHz
$t_{ASYNC\_GSR\_MPW}$	Minimum pulse width of asynchronous input	—	—	—	—	—	3.3	—	ns

Note: Synchronous GSR goes out of reset in two cycles from the clock edge where the setup time of the FF was met.

Internal System Bus Timing

Parameter	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{HCLK}	Maximum operating frequency for internal system bus HCLK.	—	200	—	200	—	200	MHz

Note: There is no minimum frequency. If HCLK is sourced from the embedded oscillator, the minimum frequency limitation of the oscillator/ divider is about 0.3 MHz. Refer to the osciallator data for missing configuration modes.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
D[n:0]	I/O	In parallel configuration modes, D[7:0] receives configuration data, and each pin is pull-up enabled. For slave serial mode, D0 is the data input. D[7:3] is the output internal status for peripheral mode when RDN is low. D[7:0] is also the first byte of MPI data pins. In MPI configuration mode, MPI selectable data bus width from 8 and 16-bit. Driven by a bus master in a write transaction. Driven by MPI in a read transaction.
DP[m:0]	I/O	MPI selectable parity data bus width from 1, 2, and 3-bit DP[0] for D[7:0], DP[1] for D[15:8], and DP[2] for D[23:16].
BUSYN/RCLK/SCK	O	During configuration in peripheral mode, high on BUSYN indicates another byte can be written to the FPGA. If a read operation is done when the device is selected, the same status is also available on D[7] in asynchronous peripheral mode. During configuration in slave parallel mode, low on BUSYN inhibits the external host from sending new data. The output is used by slave parallel and master serial modes only for decompression. During configuration in master parallel and master byte modes, RCLK is a read clock output signal to an external memory. The RCLK frequency is the same as CCLK when used with uncompressed bitstreams. RCLK will be 1/8 the frequency of CCLK when the bitstream is compressed. During configuration in SPI modes, SCK is generated by the device and connected to the CLK input of the FLASH memory.
MPI Interface (Dedicated pin)		
MPI_IRQ_N	O	MPI Interrupt request active low signal is controlled by system bus interrupt controller and may be sourced from any bus error or MPI configuration error. It can be connected to one of MPC860 IRQ pins.
MPI Interface (User I/O if MPI is not used.)		
MPI_CS0N MPI_CS1	I	MPI chip select pins, active low on MPI_CS0N while active high on MPI_CS1. Both have to be active during the whole transfer data phase. During transfer address phase, both can be inactive so that the decoding for them from address can be slow. If they are active during address phase, one cycle can be saved for sync read.
MPI_CLK	I	This is the PowerPC bus clock. It can be a source of the clock for embedded system bus. If MPI_CLK is used as system bus clock, MPI will be set into sync mode by default. All of the operation on PowerPC side of MPI are synchronized to the rising edge of this clock.
MPI_TSIZ[1:0]	I	Driven by a bus master to indicate the data transfer size for the transaction. 01 for byte, 10 for half-word, and 00 for word.
MPI_WR_N	I	Driven high indicates that a read access is in progress. Driven low indicates that a write access is in process.
MPI_BURST	I	Driven active low indicates that a burst transfer is in progress. Driven high indicates that the current transfer is not a burst.
MPI_BDIP	I	Active low “Burst Data in Process” is driven by a PowerPC processor. Asserted indicates that the second beat in front of the current one is requested by the master. Negated before the burst transfer ends to abort the burst data phase.

Pin Information Summary (Cont.)

Pin Type		1152 fcBGA			1704 fcBGA	
		LFSC/M40	LFSC/M80	LFSC/M115	LFSC/M80	LFSC/M115
Single Ended User I/O		604	660	660	904	942
Differential Pair User I/O		302	330	330	452	470
LVDS Output Pairs		78	102	102	114	132
Configuration	Dedicated	11	11	11	11	11
	Muxes/MPI sysBus	72	72	72	72	72
JTAG (excluding VCCJ)		4	4	4	4	4
Dedicated Pins		4	4	4	4	4
VCC		44	44	44	76	76
VCC12		52	52	52	88	88
VCCAUX		38	38	38	52	52
VCCIO	Bank 1	10	10	10	10	10
	Bank 2	9	9	9	12	12
	Bank 3	12	12	12	14	14
	Bank 4	12	12	12	14	14
	Bank 5	12	12	12	14	14
	Bank 6	12	12	12	14	14
	Bank 7	9	9	9	12	12
VTT	Bank 2	3	3	3	4	4
	Bank 3	3	3	3	4	4
	Bank 4	3	3	3	5	5
	Bank 5	3	3	3	5	5
	Bank 6	3	3	3	4	4
	Bank 7	3	3	3	4	4
GND		130	130	130	184	184
NC		62	6	6	52	14
Single Ended User / Differential I/O per Bank	Bank 1	80/40	80/40	80/40	80/40	80/40
	Bank 2	60/30	76/38	76/38	96/48	103/51
	Bank 3	96/48	108/54	108/54	132/66	144/72
	Bank 4	106/53	106/53	106/53	184/92	184/92
	Bank 5	106/53	106/53	106/53	184/92	184/92
	Bank 6	96/48	108/54	108/54	132/66	144/72
	Bank 7	60/30	76/38	76/38	96/48	103/51
LVDS Output Pairs Per Bank	Bank 2	15	21	21	24	27
	Bank 3	24	30	30	33	39
	Bank 6	24	30	30	33	39
	Bank 7	15	21	21	24	27
VCCJ		1	1	1	1	1
SERDES (signal + power supply)		108	108	108	212	212
Total		1152	1152	1152	1704	1704

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH11	PB47C	4	PCLKT4_6	PB54C	4	PCLKT4_6
AH10	PB47D	4	PCLKC4_6	PB54D	4	PCLKC4_6
AK12	PB49A	4	PCLKT4_0	PB55A	4	PCLKT4_0
AJ12	PB49B	4	PCLKC4_0	PB55B	4	PCLKC4_0
AF14	PB49C	4	VREF2_4	PB55C	4	VREF2_4
AE14	PB49D	4		PB55D	4	
AL11	PB51A	4	PCLKT4_5	PB57A	4	PCLKT4_5
AL10	PB51B	4	PCLKC4_5	PB57B	4	PCLKC4_5
AH9	PB51C	4		PB57C	4	
AH8	PB51D	4		PB57D	4	
AK11	PB52A	4	PCLKT4_3	PB58A	4	PCLKT4_3
AJ11	PB52B	4	PCLKC4_3	PB58B	4	PCLKC4_3
AH7	PB52C	4	PCLKT4_4	PB58C	4	PCLKT4_4
AH6	PB52D	4	PCLKC4_4	PB58D	4	PCLKC4_4
AK8	PB53A	4		PB67A	4	
AJ8	PB53B	4		PB67B	4	
AF11	PB53C	4		PB67C	4	
AD12	PB55A	4		PB69A	4	
AE12	PB55B	4		PB69B	4	
AM6	PB56A	4		PB70A	4	
AM5	PB56B	4		PB70B	4	
AC12	PB56C	4		PB70C	4	
AL6	PB57A	4		PB73A	4	
AL5	PB57B	4		PB73B	4	
AG7	PB59A	4		PB74A	4	
AG8	PB59B	4		PB74B	4	
AK6	PB60A	4		PB75A	4	
AJ6	PB60B	4		PB75B	4	
AF10	PB60C	4		PB75C	4	
AE11	PB60D	4		PB75D	4	
AM4	PB61A	4		PB77A	4	
AM3	PB61B	4		PB77B	4	
AH5	PB63A	4		PB78A	4	
AH4	PB63B	4		PB78B	4	
AK5	PB64A	4		PB79A	4	
AJ5	PB64B	4		PB79B	4	
AF8	PB64C	4		PB79C	4	
AF7	PB64D	4		PB79D	4	
AL4	PB65A	4		PB81A	4	
AL3	PB65B	4		PB81B	4	
AG5	PB65C	4		PB81C	4	
AF6	PB65D	4		PB81D	4	
AK3	PB67A	4		PB82A	4	
AJ3	PB67B	4		PB82B	4	
AE10	PB67C	4	VREF1_4	PB82C	4	VREF1_4
AD10	PB67D	4		PB82D	4	
AL2	PB68A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D	PB83A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D
AK2	PB68B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D	PB83B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
AE9	PB68C	4		PB83C	4	
AE8	PB68D	4		PB83D	4	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AD29	PL60D	6		PL84D	6	
AE31	PL61A	6		PL85A	6	
AF31	PL61B	6		PL85B	6	
AF30	PL61C	6		PL85C	6	
AF29	PL61D	6		PL85D	6	
AH33	PL62A	6		PL86A	6	
AJ33	PL62B	6		PL86B	6	
AC28	PL62C	6		PL86C	6	
AD28	PL62D	6		PL86D	6	
AH32	PL65A	6		PL89A	6	
AJ32	PL65B	6		PL89B	6	
AD27	PL65C	6		PL89C	6	
AE27	PL65D	6	VREF2_6	PL89D	6	VREF2_6
AG34	PL66A	6		PL90A	6	
AH34	PL66B	6		PL90B	6	
AC26	PL66C	6		PL90C	6	
AB26	PL66D	6		PL90D	6	
AK33	PL67A	6		PL91A	6	
AL33	PL67B	6		PL91B	6	
AG30	PL67C	6		PL91C	6	
AH30	PL67D	6		PL91D	6	
AL34	PL69A	6		PL93A	6	
AM34	PL69B	6		PL93B	6	
AJ30	PL69C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F	PL93C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F
AK30	PL69D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F	PL93D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F
AJ31	PL70A	6		PL94A	6	
AH31	PL70B	6		PL94B	6	
AD26	PL70C	6		PL94C	6	
AD25	PL70D	6		PL94D	6	
AL32	PL71A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E	PL95A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
AL31	PL71B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E	PL95B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E
AG29	PL71C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A	PL95C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A
AG28	PL71D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A	PL95D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A
AF28	XRES	-		XRES	-	
AF27	TEMP	6		TEMP	6	
AM33	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B
AN33	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B
AH29	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D
AJ29	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D
AM32	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C
AM31	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C
AG27	PB4C	5		PB4C	5	
AG26	PB4D	5		PB4D	5	
AL29	PB5A	5		PB5A	5	
AL28	PB5B	5		PB5B	5	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AG18	PB42C	5		PB61C	5	
AF18	PB42D	5		PB61D	5	
AP19	PB43A	5		PB63A	5	
AP18	PB43B	5		PB63B	5	
AJ18	PB43C	5		PB63C	5	
AH18	PB43D	5		PB63D	5	
AP17	PB45A	4		PB65A	4	
AP16	PB45B	4		PB65B	4	
AJ17	PB45C	4		PB65C	4	
AH17	PB45D	4		PB65D	4	
AN17	PB46A	4		PB66A	4	
AN16	PB46B	4		PB66B	4	
AE17	PB46C	4		PB66C	4	
AD17	PB46D	4		PB66D	4	
AK17	PB47A	4		PB67A	4	
AK16	PB47B	4		PB67B	4	
AG17	PB47C	4		PB67C	4	
AF17	PB47D	4		PB67D	4	
AM16	PB49A	4		PB69A	4	
AM15	PB49B	4		PB69B	4	
AJ15	PB49C	4		PB69C	4	
AJ14	PB49D	4		PB69D	4	
AL16	PB50A	4		PB70A	4	
AL15	PB50B	4		PB70B	4	
AG16	PB50C	4		PB70C	4	
AF16	PB50D	4		PB70D	4	
AP15	PB51A	4		PB71A	4	
AP14	PB51B	4		PB71B	4	
AH15	PB51C	4		PB71C	4	
AH14	PB51D	4		PB71D	4	
AN15	PB53A	4	PCLKT4_2	PB74A	4	PCLKT4_2
AN14	PB53B	4	PCLKC4_2	PB74B	4	PCLKC4_2
AE16	PB53C	4	PCLKT4_7	PB74C	4	PCLKT4_7
AD16	PB53D	4	PCLKC4_7	PB74D	4	PCLKC4_7
AK15	PB54A	4	PCLKT4_1	PB75A	4	PCLKT4_1
AK14	PB54B	4	PCLKC4_1	PB75B	4	PCLKC4_1
AG15	PB54C	4	PCLKT4_6	PB75C	4	PCLKT4_6
AG14	PB54D	4	PCLKC4_6	PB75D	4	PCLKC4_6
AM13	PB55A	4	PCLKT4_0	PB77A	4	PCLKT4_0
AM12	PB55B	4	PCLKC4_0	PB77B	4	PCLKC4_0
AJ12	PB55C	4	VREF2_4	PB77C	4	VREF2_4
AJ11	PB55D	4		PB77D	4	
AL13	PB57A	4	PCLKT4_5	PB79A	4	PCLKT4_5
AL12	PB57B	4	PCLKC4_5	PB79B	4	PCLKC4_5
AH12	PB57C	4		PB79C	4	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AJ9	PB78C	4		PB117C	4	
AJ8	PB78D	4		PB117D	4	
AP3	PB79A	4		PB119A	4	
AN3	PB79B	4		PB119B	4	
AF10	PB79C	4		PB119C	4	
AE10	PB79D	4		PB119D	4	
AL7	PB81A	4		PB121A	4	
AL6	PB81B	4		PB121B	4	
AK7	PB81C	4		PB121C	4	
AK6	PB81D	4		PB121D	4	
AN5	PB82A	4		PB123A	4	
AN4	PB82B	4		PB123B	4	
AH9	PB82C	4	VREF1_4	PB123C	4	VREF1_4
AH8	PB82D	4		PB123D	4	
AM3	PB83A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D	PB124A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D
AM4	PB83B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D	PB124B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
AG9	PB83C	4		PB124C	4	
AG8	PB83D	4		PB124D	4	
AN2	PB85A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B	PB125A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B
AM2	PB85B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B	PB125B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B
AJ6	PB85C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C	PB125C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C
AH6	PB85D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C	PB125D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C
AF7	PROBE_VCC	-		PROBE_VCC	-	
AF8	PROBE_GND	-		PROBE_GND	-	
AG7	PR71D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A	PR95D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A
AG6	PR71C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A	PR95C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A
AL4	PR71B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E	PR95B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
AL3	PR71A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E	PR95A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
AD10	PR70D	3		PR94D	3	
AD9	PR70C	3		PR94C	3	
AH4	PR70B	3		PR94B	3	
AJ4	PR70A	3		PR94A	3	
AK5	PR69D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F	PR93D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F
AJ5	PR69C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F	PR93C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F
AM1	PR69B	3		PR93B	3	
AL1	PR69A	3		PR93A	3	
AH5	PR67D	3		PR91D	3	
AG5	PR67C	3		PR91C	3	
AL2	PR67B	3		PR91B	3	
AK2	PR67A	3		PR91A	3	
AB9	PR66D	3		PR90D	3	
AC9	PR66C	3		PR90C	3	
AH1	PR66B	3		PR90B	3	
AG1	PR66A	3		PR90A	3	
AE8	PR65D	3	VREF2_3	PR89D	3	VREF2_3

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
C32	VCC12	-		VCC12	-	
E34	NC	-		PL22A	7	
F34	NC	-		PL22B	7	
F33	NC	-		PL24A	7	
G33	NC	-		PL24B	7	
K30	NC	-		PL25A	7	
L30	NC	-		PL25B	7	
G34	NC	-		PL26A	7	
H34	NC	-		PL26B	7	
M32	NC	-		PL39A	7	
N32	NC	-		PL39B	7	
P28	NC	-		PL39C	7	
R28	NC	-		PL39D	7	
J34	NC	-		PL41A	7	
K34	NC	-		PL41B	7	
P30	NC	-		PL41C	7	
R30	NC	-		PL41D	7	
W34	NC	-		PL59A	6	
Y34	NC	-		PL59B	6	
W32	NC	-		PL61A	6	
Y32	NC	-		PL61B	6	
AA34	NC	-		PL64A	6	
AB34	NC	-		PL64B	6	
AC34	NC	-		PL67A	6	
AD34	NC	-		PL67B	6	
Y30	NC	-		PL68A	6	
AA30	NC	-		PL68B	6	
AB33	NC	-		PL69A	6	
AC33	NC	-		PL69B	6	
AC2	NC	-		PR69B	3	
AB2	NC	-		PR69A	3	
AA5	NC	-		PR68B	3	
Y5	NC	-		PR68A	3	
AD1	NC	-		PR67B	3	
AC1	NC	-		PR67A	3	
AB1	NC	-		PR64B	3	
AA1	NC	-		PR64A	3	
Y3	NC	-		PR61B	3	
W3	NC	-		PR61A	3	
Y1	NC	-		PR59B	3	
W1	NC	-		PR59A	3	
R5	NC	-		PR41D	2	
P5	NC	-		PR41C	2	
K1	NC	-		PR41B	2	
J1	NC	-		PR41A	2	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AC19	VTT_5	5		VTT_5	5	
AC20	VTT_5	5		VTT_5	5	
AD22	VTT_5	5		VTT_5	5	
AB24	VTT_6	6		VTT_6	6	
W23	VTT_6	6		VTT_6	6	
Y23	VTT_6	6		VTT_6	6	
N24	VTT_7	7		VTT_7	7	
R23	VTT_7	7		VTT_7	7	
T23	VTT_7	7		VTT_7	7	
M12	VDDAX25_R	-		VDDAX25_R	-	
M23	VDDAX25_L	-		VDDAX25_L	-	
Y16	GND	-		GND	-	
Y14	GND	-		GND	-	
N21	VCC12	-		VCC12	-	
P22	VCC12	-		VCC12	-	
AA22	VCC12	-		VCC12	-	
AB21	VCC12	-		VCC12	-	
AB14	VCC12	-		VCC12	-	
AA13	VCC12	-		VCC12	-	
P13	VCC12	-		VCC12	-	
N14	VCC12	-		VCC12	-	
G26	NC	-		NC	-	
G9	NC	-		NC	-	
J12	NC	-		NC	-	
H12	NC	-		NC	-	
H23	NC	-		NC	-	
J23	NC	-		NC	-	

1. Differential pair grouping within a PCI is A (True) and B (complement) and C (True) and D (Complement).
2. The LatticeSC/M40 and LatticeSC/M80 in an 1152-pin package support a 32-bit MPI interface.

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
U22	VCCAUX	-	
V13	VCCAUX	-	
V22	VCCAUX	-	
V23	VCCAUX	-	
W13	VCCAUX	-	
W22	VCCAUX	-	
Y21	GND	-	
Y25	GND	-	
C18	VCCIO1	-	
D17	VCCIO1	-	
F16	VCCIO1	-	
G19	VCCIO1	-	
J20	VCCIO1	-	
K12	VCCIO1	-	
K15	VCCIO1	-	
L23	VCCIO1	-	
Y9	GND	-	
J9	VCCIO1	-	
E3	VCCIO2	-	
G6	VCCIO2	-	
H4	VCCIO2	-	
K7	VCCIO2	-	
L3	VCCIO2	-	
M11	VCCIO2	-	
N6	VCCIO2	-	
P4	VCCIO2	-	
R9	VCCIO2	-	
AA3	VCCIO3	-	
AB7	VCCIO3	-	
AC10	VCCIO3	-	
AD4	VCCIO3	-	
AE6	VCCIO3	-	
AG3	VCCIO3	-	
AK4	VCCIO3	-	
T7	VCCIO3	-	
U3	VCCIO3	-	
V4	VCCIO3	-	
W6	VCCIO3	-	
Y10	VCCIO3	-	
AD12	VCCIO4	-	
AF15	VCCIO4	-	
AF9	VCCIO4	-	
AH10	VCCIO4	-	

Industrial

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA15E-6FN256I	-6	Lead-Free fpBGA	256	IND	15.2
LFSC3GA15E-5FN256I	-5	Lead-Free fpBGA	256	IND	15.2
LFSC3GA15E-6FN900I	-6	Lead-Free fpBGA	900	IND	15.2
LFSC3GA15E-5FN900I	-5	Lead-Free fpBGA	900	IND	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA15EP1-6FN256I	-6	Lead-Free fpBGA	256	IND	15.2
LFSCM3GA15EP1-5FN256I	-5	Lead-Free fpBGA	256	IND	15.2
LFSCM3GA15EP1-6FN900I	-6	Lead-Free fpBGA	900	IND	15.2
LFSCM3GA15EP1-5FN900I	-5	Lead-Free fpBGA	900	IND	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA25E-6FN900I	-6	Lead-Free fpBGA	900	IND	25.4
LFSC3GA25E-5FN900I	-5	Lead-Free fpBGA	900	IND	25.4
LFSC3GA25E-6FFN1020I[1]	-6	Lead-Free Organic fcBGA	1020	IND	25.4
LFSC3GA25E-5FFN1020I[1]	-5	Lead-Free Organic fcBGA	1020	IND	25.4
LFSC3GA25E-6FFAN1020I	-6	Lead-Free Organic fcBGA Revision 2	1020	IND	25.4
LFSC3GA25E-5FFAN1020I	-5	Lead-Free Organic fcBGA Revision 2	1020	IND	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA25EP1-6FN900I	-6	Lead-Free fpBGA	900	IND	25.4
LFSCM3GA25EP1-5FN900I	-5	Lead-Free fpBGA	900	IND	25.4
LFSCM3GA25EP1-6FFN1020I[1]	-6	Lead-Free Organic fcBGA	1020	IND	25.4
LFSCM3GA25EP1-5FFN1020I[1]	-5	Lead-Free Organic fcBGA	1020	IND	25.4
LFSCM3GA25EP1-6FFAN1020I	-6	Lead-Free Organic fcBGA Revision 2	1020	IND	25.4
LFSCM3GA25EP1-5FFAN1020I	-5	Lead-Free Organic fcBGA Revision 2	1020	IND	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA40E-6FFN1020I[1]	-6	Lead-Free Organic fcBGA	1020	IND	40.4
LFSC3GA40E-5FFN1020I[1]	-5	Lead-Free Organic fcBGA	1020	IND	40.4
LFSC3GA40E-6FFAN1020I	-6	Lead-Free Organic fcBGA Revision 2	1020	IND	40.4
LFSC3GA40E-5FFAN1020I	-5	Lead-Free Organic fcBGA Revision 2	1020	IND	40.4
LFSC3GA40E-6FCN1152I[2]	-6	Lead-Free Ceramic fcBGA	1152	IND	40.4
LFSC3GA40E-5FCN1152I[2]	-5	Lead-Free Ceramic fcBGA	1152	IND	40.4
LFSC3GA40E-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	40.4
LFSC3GA40E-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.